

# 2N3820

## **P-Channel General Purpose Amplifier**

- This device is designed primarily for low level audio and general purpose applications with high impedance signal sources.
- · Sourced from process 89.



1. Drain 2. Gate 3. Source

# **Epitaxial Silicon Transistor**

# **Absolute Maximum Ratings\*** $T_C=25$ °C unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{DG}$	Drain-Gate Voltage	-20	V
$V_{GS}$	Gate-Source Voltage	20	V
I <sub>GF</sub>	Forward Gate Current	10	mA
T <sub>STG</sub>	Storage Temperature Range	-55 ~ 150	°C

<sup>\*</sup> This ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

# $\textbf{Electrical Characteristics} \ \, \textbf{T}_{\text{C}} = 25 ^{\circ} \text{C unless otherwise noted}$

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Chara	Off Characteristics					
V <sub>(BR)GSS</sub>	Gate-Source Breakdwon Voltage	$I_{G} = 10\mu A, V_{DS} = 0$	20			V
I <sub>GSS</sub>	Gate Reverse Current	$V_{GS} = 10V, V_{DS} = 0$			20	nA
V <sub>GS</sub> (off)	Gate-Source Cutoff Voltage	$V_{DS} = -10V, I_{D} = -10\mu A$			8.0	V
On Characteristics						
I <sub>DSS</sub>	Zero-Gate Voltage Drain Current *	$V_{DS} = -10V, V_{GS} = 0$	-0.3		-15	mA
Small Signal Characteristics						
gfs	Forward Transfer Conductance	$V_{DS} = -10V, V_{GS} = 0, f = 1.0KHz$	800		5000	μmhos
C <sub>iss</sub>	Input Capacitance	$V_{DS} = -10V, V_{GS} = 0, f = 1.0KHz$			32	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	$V_{DS} = -10V, V_{GS} = 0, f = 1.0KHz$			16	pF
* Pulse Test: Pulse Width < 300ms Duty Cycle < 2%						

# Thermal Characteristics T<sub>A</sub>=25°C unless otherwise noted

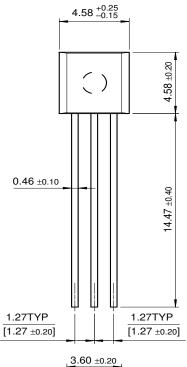
Symbol	Parameter	Max.	Units
P <sub>D</sub>	Total Device Dissipation	350	mW
	Derate above 25°C	2.8	mW/°C
$R_{ heta JC}$	Thermal Resistance, Junction to Case	125	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W

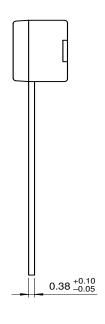
<sup>\*</sup> Device mounted on FR-4 PCB 1.6" × 1.6" × 0.06"

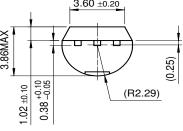
These rating are based on a maximum junction temperature of 150 degrees C.
These are steady limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

# **Package Dimensions**

TO-92







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EnSigna™	I <sup>2</sup> C™	OCXTM	RapidConfigure™	UHC™
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The Power Franci	hise™	OPTOLOGIC <sup>®</sup>	SILENT SWITCHER®	VCX™
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